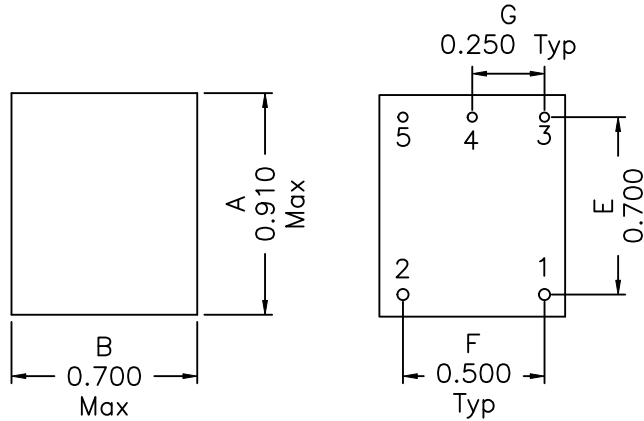
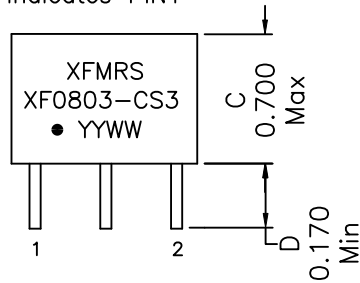


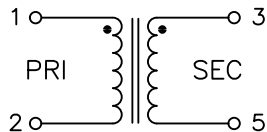
**1. Mechanical Dimensions:**



Dot Indicates PIN1



**2. Schematic:**



**3. Electrical Specifications: @25°C**

Isolation: Pri to Sec 3750Vac 1Min/5000Vac 1Sec

SEC Turns: 200 T

SEC OCL: 80.0mH Minimum @10KHz 1.0V

SEC Q: 40 Minimum @10KHz 0.1V

DC Resistance: 4.70 Ohms Maximum

Terminating Resistance: 200 Ohms Max

Pri Unipolar Amp-microsec. Max Rating: 600

Pri bipolar Amp-microsec. Max Rating: 1200

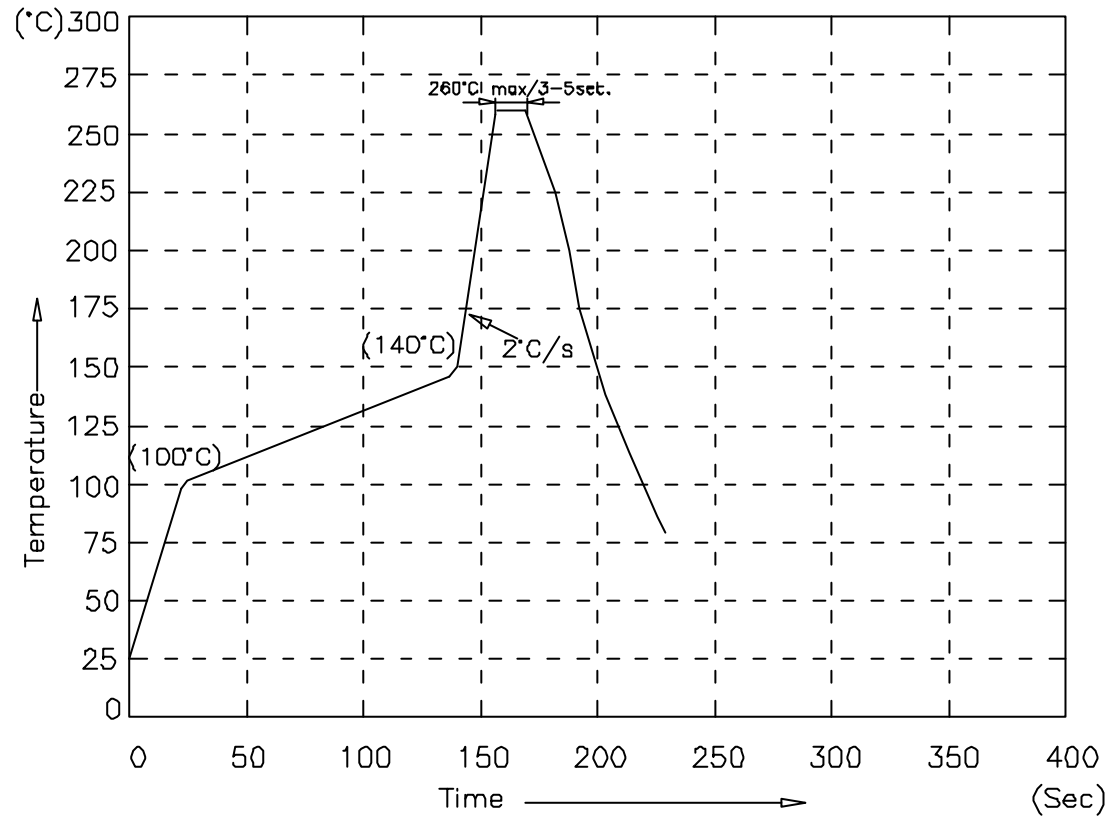
**Notes:**

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. Electrical and mechanical specifications 100% tested
9. RoHS Compliant Component
10. Internal winding spacing: 52mils Pri to Sec

DOC. REV: A/10

<b>XFMR5®</b> www.XFMR5.com	Title: Current Sense Xfmr		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in Inch	P/N: XF0803-CS3	REV. A
SHEET 1 OF 1	DWN.	Yu	Nov-08-19
	CHK.	YK Liao	Nov-08-19
	APP.	BW	Nov-08-19

Recommended wave soldering profile  
for Lead-free Through-hole component.



NOTE:

1. Recommend the wave temperature 245°C–260°C. The maximum soldering temperature should be less than 260°C
2. Do not apply stress on plastics when temperature is over 85°C
3. The soldering profile applies to the lead free soldering (Sn/Cu alloy).
4. No more than 1 cycle.

DOC. REV A/2

**PROPRIETARY**

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<b>XFMRS Inc.</b> <a href="http://www.XFMRS.com">www.XFMRS.com</a>	Title: Soldering profile			
	UNLESS OTHERWISE SPECIFIED TOLERANCES: N/A		P/N: TH component	REV. A
		DWN.	Juan Mao	Apr-12-07
		CHK.	YK Liao	Apr-12-07
SHEET 1 OF 1		APP.	BW	Apr-12-07